826469-8 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 826469-8 PCB Mount Header, Vertical, Board-to-Board, 16 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 16

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Partially Shrouded



Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	16
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Body Features	
Connector Profile	Standard
Primary Product Color	Black
Contact Features	

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PCB Contact Termination Area Plating Material Thickness	3 µm
Mating Pin Diameter	.63 mm[.025 in]
Contact Shape & Form	Round
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.8 μm[31.5 μin]
Contact Type	Pin
Contact Current Rating (Max)	5 A
Termination Features	
Round Termination Post & Tail Diameter	.63 mm[.025 in]
Termination Post & Tail Length	3.2 mm[.126 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Retention	With
Mating Retention Type	Detent Latching
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	РСТ
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
	00/02/2022

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Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Agency/Standard	CSA, UL
Approved Standards	CSA LR7189, CUL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	200
Packaging Type	Box
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023

(233)

Does not contain REACH SVHC

Not Low Halogen - contains Br or Cl > 900 ppm.

Pin-in-Paste capable to 260°C

Halogen Content

Solder Process Capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

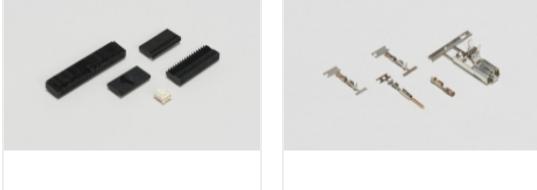
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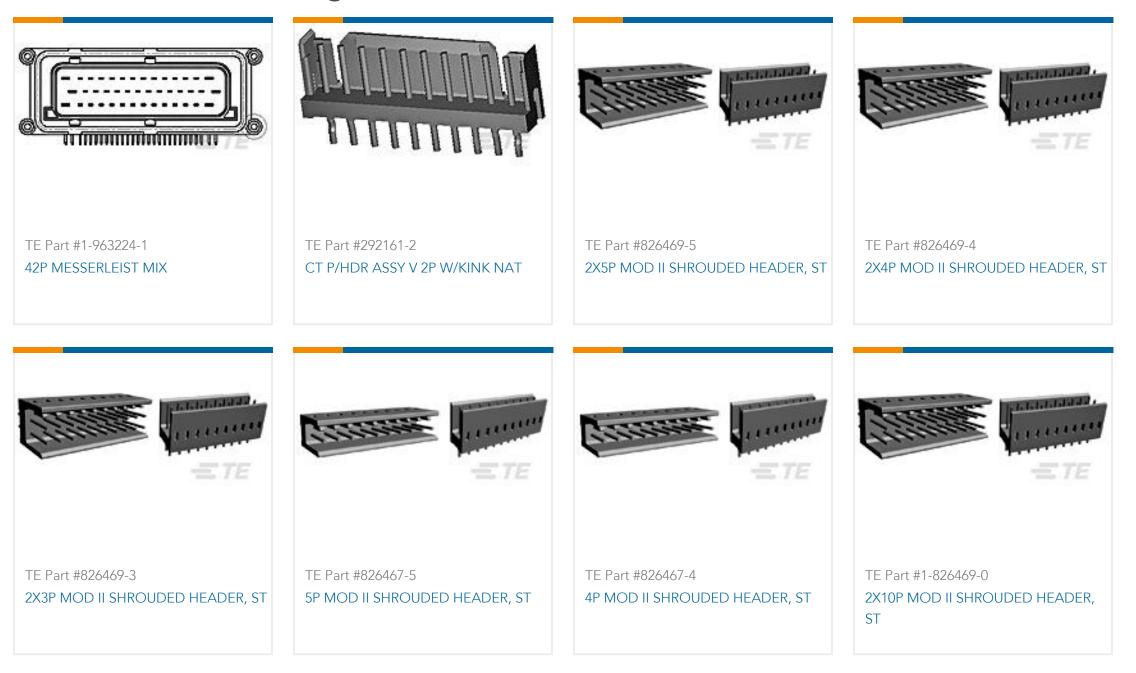
Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies	Wire-to-Board Connector Contacts(65)
& Housings(5)	

Customers Also Bought



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Documents

Product Drawings 2X8P MOD II SHROUDED HEADER, ST

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_826469-8_E.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_826469-8_E.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_826469-8_E.3d_stp.zip

English

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Agency Approvals UL Report

English